

Supplementary material

Use of microcutting for high throughput electrode patterning on a flexible substrate

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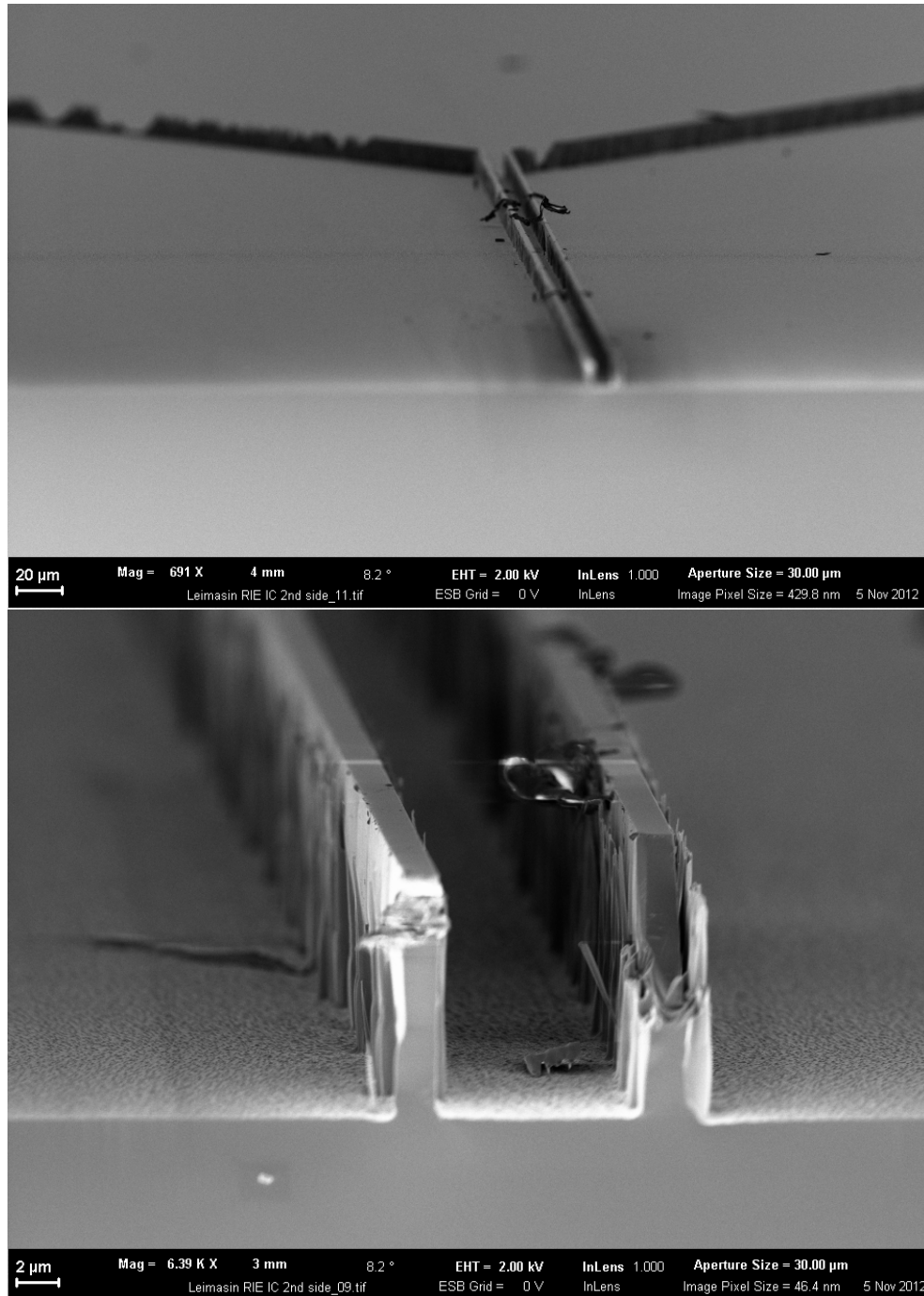


Figure 1: SEM images of stamp 2 (two different magnifications).

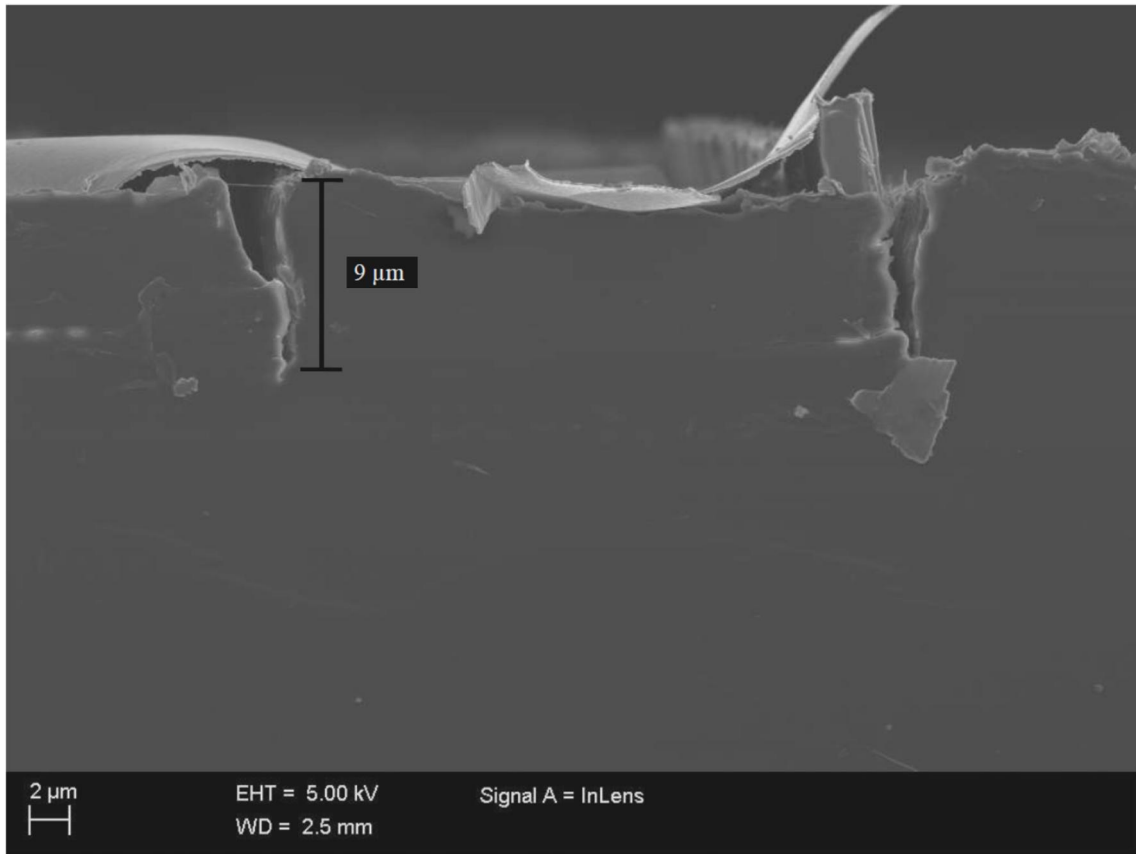


Figure 2: SEM image of the cross-section profile of microcut sample using NIL-tool and stamp 2.

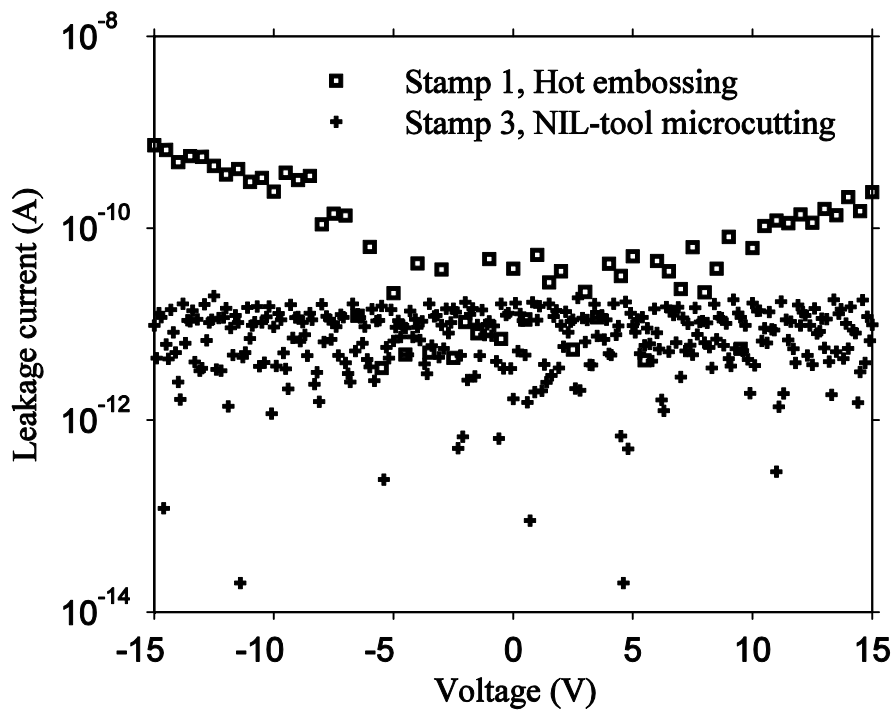


Figure 3: Leakage currents between the adjacent electrodes patterned by hot embossing with stamp 1 and NIL-tool microcutting with stamp 3.